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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): An electronic substrate suitable for being included in a stack including said electronic substrate and another electronic substrate and suitable for being connected to the other electronic substrate and to an input-output interface, said electronic substrate comprising:

a frame made of a material with a high thermal conductivity having a plurality of sides, a first side of said electronic substrate intending to be in contact with a corresponding side of the frame of another neighboring substrate so as to provide thermal dissipation of the electronic substrates and a second side of said electronic substrate comprising an interconnection element intended to provide electrical interconnection between said electronic substrate and the other electronic substrate by means of a routing circuit suitable for being matched according to the electrical interconnection and/or between said electronic substrate and the input-output interface, the frame having a bottom also having a material with a high thermal conductivity, wherein the bottom includes a phase-change cooling element;

wherein said electronic substrate has conductive tracks and in that the interconnection element includes a first conductive element intended to be in contact with the tracks;

wherein the interconnection element also includes a second conductive element intended to be connected to the routing circuit with a view to connecting this second conductive element to a conductive element of the interconnection element of the frame of the other neighboring electronic substrate.

2. (Canceled)

3. (Canceled)

4. (Canceled)

5. (Canceled)

6. (Currently Amended): The electronic substrate as claimed in claim [[4]] 1, wherein the conductive element comprises conductive rings inserted between two insulators.

7. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the routing circuit is a multilayer printed circuit.

8. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the frame includes reversible positioning means intended to position said frame with respect to the frame of the other neighboring electronic substrate and/or with respect to the input-output interface.

9. (Previously Presented): The electronic substrate as claimed in claim 8, wherein the reversible positioning means include first centering pins and reinforcements.

10. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the frame includes second centering pins intended to position said substrate in its frame.

11. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the substrate is fixed to its frame by means of an adhesive.

12. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the material with a high conductivity is aluminum or copper or graphite.

13. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the substrate includes a support made of epoxy or ceramic or gallium arsenide or of a metallized insulator.

14. (Previously Presented): The electronic substrate as claimed in claim 1, wherein the frame has four sides and in that two first sides are intended for the thermal dissipation and two second sides each include an interconnection element.

15. (Previously Presented): The electronic substrate as claimed in claim 1, wherein it has a surface area of approximately 5 X 5 cm².

16. (Currently Amended): An electronic module having an input-output interface and a stack of a plurality of electronic substrates as claimed in claim 1;

wherein it furthermore has a package suitable for holding the stack of framed electronic substrates;

wherein it includes a cover comprising the input-output interface; and

wherein cover including means for fastening to the package and in that the fastening means are suitable for stabilizing the framed substrates in the package.

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Currently Amended): The electronic module as claimed in claim [[19]] 16, wherein the fastening means are reversible.

21. (Currently Amended): The electronic module as claimed in claim [[17]] 16, wherein the package consists of a material with a high thermal conductivity.

22. (Currently Amended): The electronic module as claimed in claim [[17]] 16, wherein the package has a specific interior profile and in that each frame has an exterior profile complementary to that of the package, with a view to facilitating pre-positioning of the frames in the package.